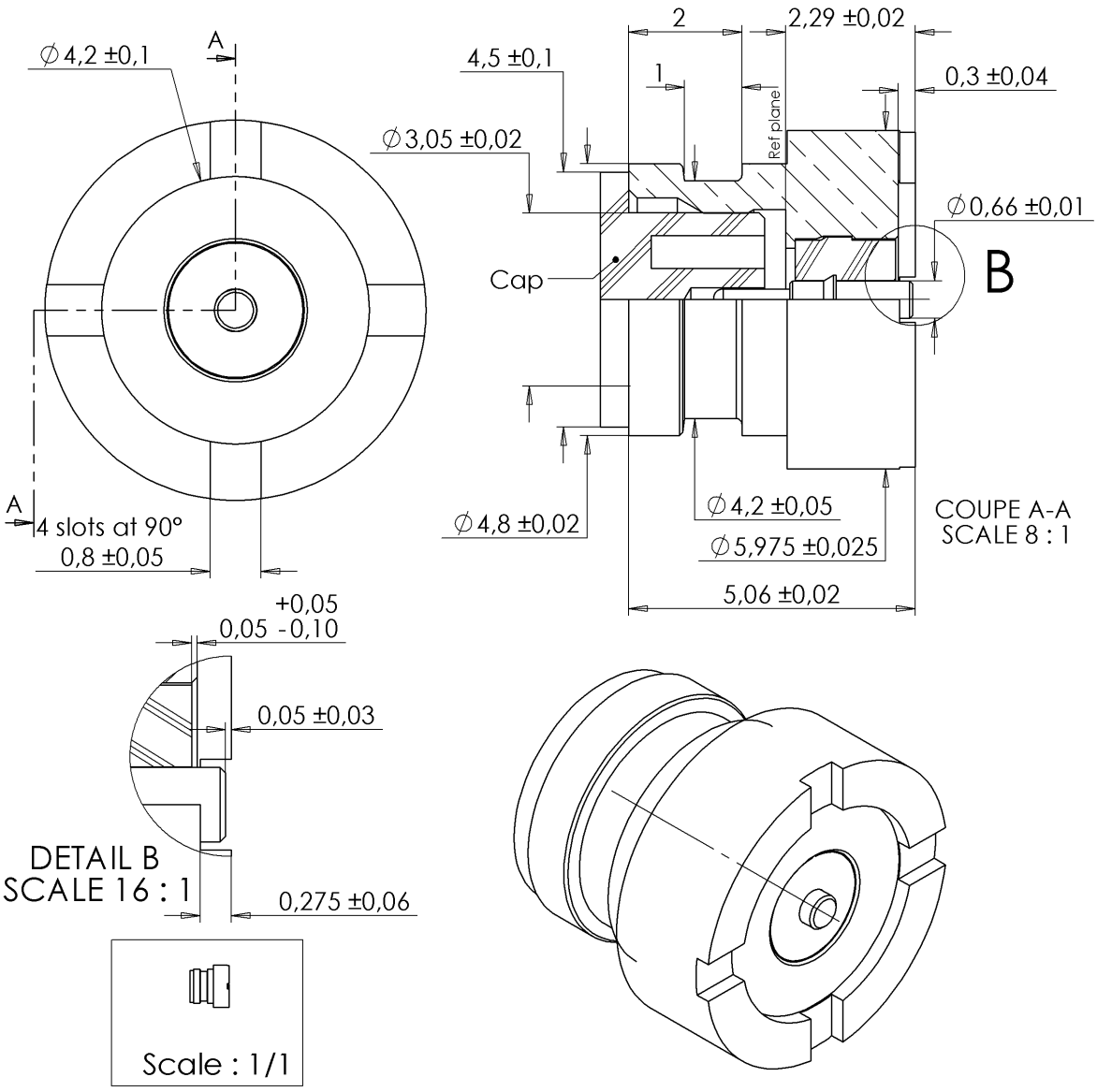
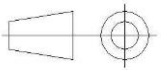
PAGE **1/6**	ISSUE **2035A**	SERIES **SMP-S-LOCK**	PART NUMBER **R232L00020**



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (µm)
Body	**BRASS**	**GOLD 0.5 OVER NICKEL 2**
Center contact	**BERYLLIUM COPPER**	**GOLD 1.3 OVER NICKEL2**
Outer contact		
Insulator	**PTFE**	
Gasket		
Others parts	**PTFE**	
-	-	-
-	-	-

PACKAGING

Standard	Unit	Other
1	-	Contact us

ELECTRICAL CHARACTERISTICS

Impedance			50	Ω
Frequency			DC-18	GHz
VSWR	1.03	+	0,0150	x F(GHz) Maxi
Insertion loss			0.02+0.12	√F(GHz) dB Maxi
RF leakage		- (	NA	- F(GHz)) dB Maxi
Voltage rating			335	Vrms Maxi
Dielectric withstanding voltage			500	Vrms mini
Insulation resistance			5000	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	6.8	N mini
Axial force – Opposite end	NA	N mini
Torque	NA	N.cm mini
Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm
Mating life	100	Cycles Maxi
Weight	0,7500	g Maxi

ENVIRONMENTAL

Operating temperature	-65/+165	°C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

SPECIFICATION

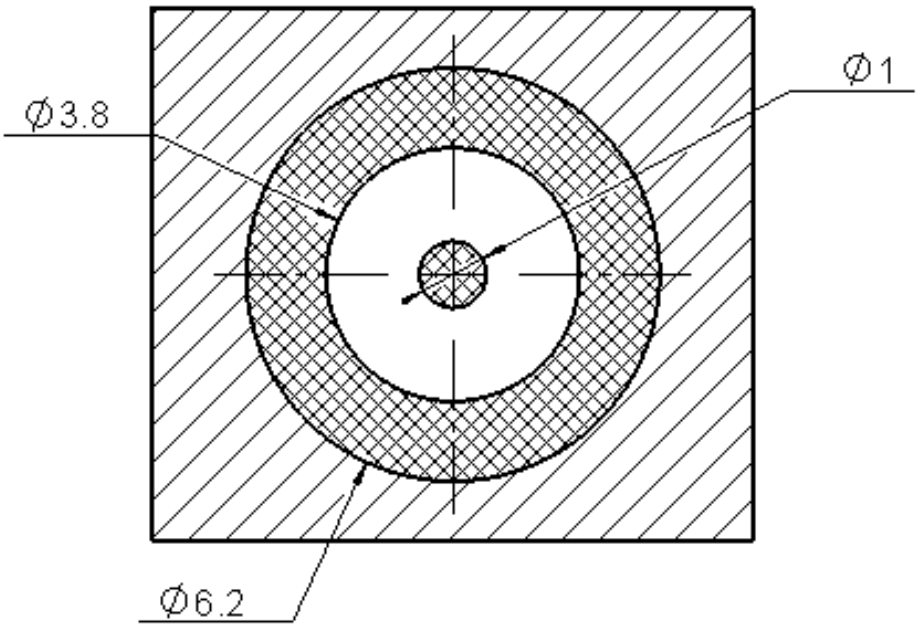
RAD-GEN-CONN 001
RAD-DET-CONN 019

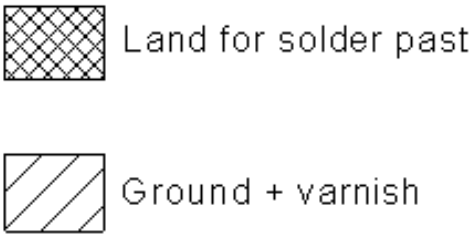
OTHER CHARACTERISTICS

Assembly instruction:

Others:

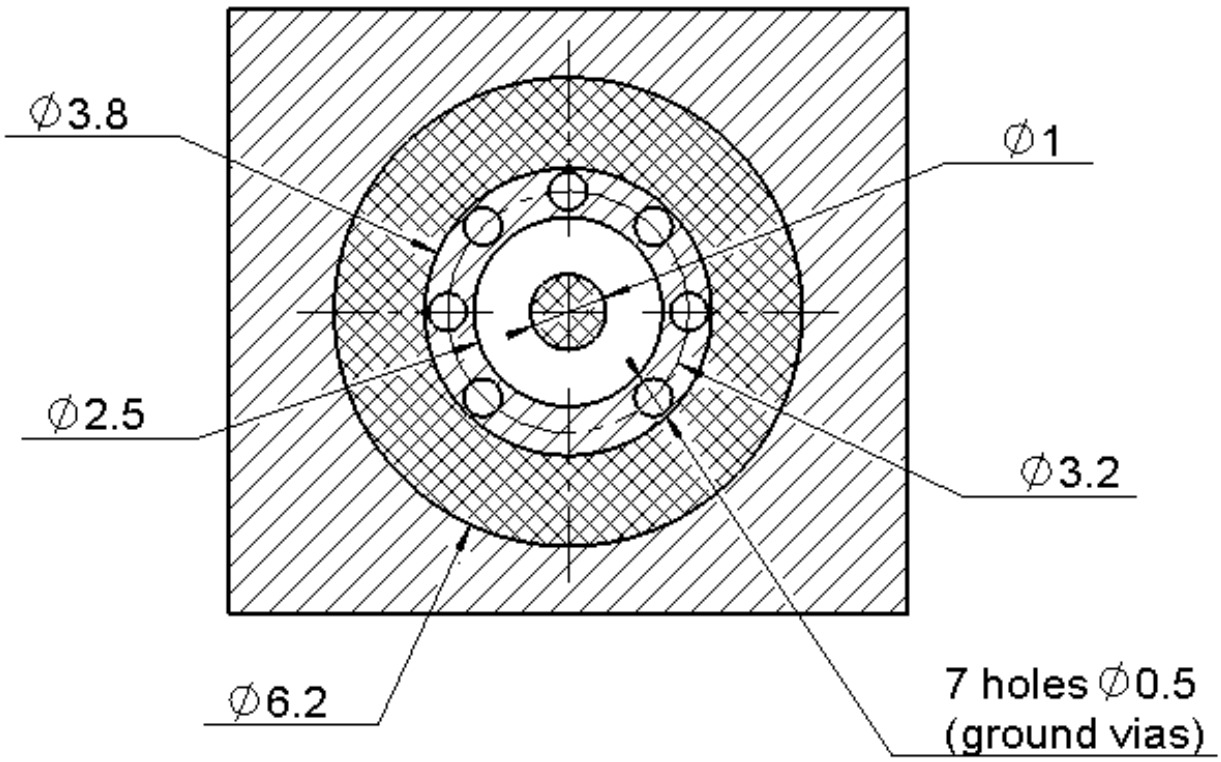
STANDARD PAD (RADIALL RECOMMANDATION)





-The landing pad for center contact should be linked to the stripline using a filled via.
-Upper and lower ground planes should be linked using vias.

RT DUROID 6002 (30 mils) PAD (RADIALL RECOMMANDATION)



Land for solder past

Ground + varnish

-The landing pad for center contact should be linked to the stripline using a filled via.
-Upper and lower ground planes should be linked using vias.

SOLDER PROCEDURE

1. **Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 µm. Verify that the edges of the zone are clean.**

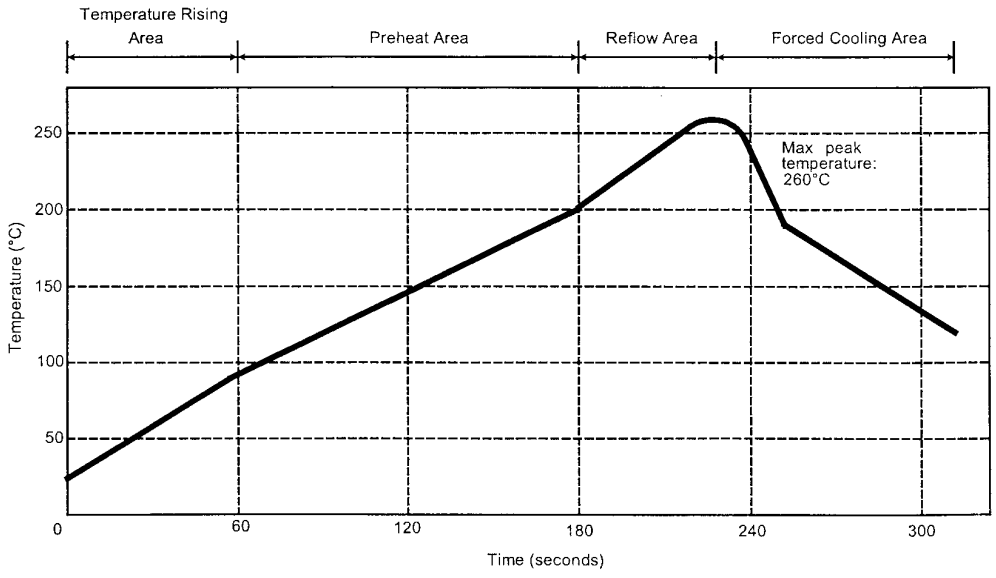
2. **Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.**

3. **This process of soldering has been tested with convection oven .Below please find, the typical profile to use.**

4. **The cleaning of printed circuit boards is not obliged.**

5. **Verification of solder joints and position of the component by visual inspection.**

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

PAGE **6/6**	ISSUE **2035A**	SERIES **SMP-S-LOCK**	PART NUMBER **R232L00020**